



SUBSTITUTE FORM PTO-1449
U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

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9325-49 (149169)

SERIAL NO.
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INFORMATION DISCLOSURE CITATION

APPLICANT:
Scott W. Huffer, et al.

FILING DATE
April 4, 2001

GROUP
1773

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA	4,008,115	2/15/77	Fairbanks, et al.	156	267	
	AB	4,810,745	3/7/89	Pike, et al.	524	516	
	AC	5,888,649	3/30/99	Curatolo, et al.	428	352	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AD	CH 664 971 A	04/15/88	Switzerland	C08L	7/00		
	AE	EP 0 870 695 A1	10/14/98	EPO	B65D	65/14		

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	AG	Novelty Radiation Curable Silicone Acrylates with Extraordinary Features, Dr. Dietmar Wewers, Paper 1, Radtech Europe Edinburgh 29 th /Sept-2nd Oct. 1991
	AH	UV/EB Paper Coatings: Old and New, D.J. Cyterski; Polymers, Laminations and Coatings Conference 1984
	AI	Cure for Coating, Alexander T, Packaging Week, Vol. 3, no. 12, 29 July 1987
	AJ	Electron Radiation Curing Resin Composition and Composite Sheet Material Produced by Using the Composition, Japanese Patent Application No. 11105138 (Publ. No. 2000297218 A)
	AK	Application & Film Formation: UV and EB Curing, S.J. Bett et al., Jocca 1990
	AL	Oberflächenveredelung mit UV-und EB-härtenden Silicon-Acryaten als Trennbeschichtung, Günter M. Miles, Coating 2/96
	AM	Radiation-curable additives for coatings and printing inks, Karen Bowling et al., PCCJ, August 1997
	AN	Electron Beam Curing of Epoxy-Silicone Release Coatings, Stuart R. Kerr III, Adhesive Age, 1998
	AO	Manufacturers of Waterbase, UV+EB Curable Coatings, Varnishes and Adhesives; Bags, Multiwall & Others Move to High End Graphics, Cork Tech TalkNews; April, 2000
	AP	Neue UV-härtbare System für Überzugslacke, Kaschier-und Haftklebstoffe; 21. Munchner Klebstoff-und Veredelungsseminar, 1996



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<input checked="" type="checkbox"/>	AQ	Present Status of Radiation Processing in Asia; RadTech Asia 1991
<input checked="" type="checkbox"/>	AR	Silicone Acrylate System, Ebbrecht T. et al., EuroCoat, 9/1992
<input checked="" type="checkbox"/>	AS	Today's Electron Beam: A Competitive Advantage for Packaging, Edward F. Maguire, RadTech Report, September/October 1997
EXAMINER	DATE CONSIDERED	
<i>[Handwritten signatures and initials over the table rows]</i>		
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.		

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
<i>AD</i>	AA	5,492,733	2/20/96	D'Anna et al.	427	517	

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		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	NO
<i>AD</i>	AB	GB 2 298 818	9/18/96	United Kingdom	B41M	3/00	N/A	
<i>AD</i>	AC	GB 2 320 911	7/8/98	United Kingdom	B32B	5/18	N/A	
<i>AD</i>	AD	WO 96/29205	9/26/96	WIPO	B41M	7/00	N/A	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>AD</i>	AE	Japanese Patent Abstract, No. 02-117826
<i>AD</i>	AF	Japanese Patent Abstract, No. 07-186514
EXAMINER		DATE CONSIDERED <i>4/25/05</i>

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